

# IEEE IITC 2025

The 28th edition of the IEEE International Interconnect Technology Conference

June 2-5, 2025

Westin Josun Busan, Busan, Korea

**The 28th edition of the IEEE International Interconnect Technology Conference (IEEE IITC) will be held at the Westin JOSUN hotel in Busan, Korea on June 2-5, 2025. This is the first IITC held in Korea.**

Authors are encouraged to submit their original work describing innovative research and development in the critically important field of on-chip interconnects. The conference seeks papers on all aspects of BEOL/MOL interconnects and metallization, including design, unit process, integration and reliability.

**The deadline for submission of abstracts is February 21, 2025.**

IITC is sponsored by the IEEE Electron Devices Society and is co-sponsored by the Japan Society of Applied Physics as the premier conference for interconnect technology devoted to leading-edge research in the field of advanced metallization and 3D integration for ULSI IC applications. The conference seeks papers on all aspects of BEOL/MOL interconnects and metallization, including design, unit process, integration and reliability.

## APPLICATIONS OF INTEREST

- Advanced interconnects: low-k interconnects, optical, wireless, and carbon-based interconnects, Airgap, 1D/2D interconnects, beyond Cu...
- Emerging BEOL Integration flows such as semi-damascene
- 3D integration & packaging concerns: Wafer-to-Wafer/Chip-to-Wafer bonding, RDL's and Interposers, Through Si Via, Non-destructive, high throughput methods to identify defects, backside power distribution network (BSPDN), thermal management
- Contacts on MOS devices: Silicide, III-V, 2D materials...
- Memory architecture: CBRAM, PCRAM, ReRAM, MRAM, FeRAM, DRAM, 3DNAND...
- Novel System and Emerging Technology: Energy harvesting, brain-inspired computing...
- Novel Form Factors: flexible electronics, wearables...

## TOPICS OF INTEREST

- Process integration, advanced patterning for MOL/BEOL
- Materials and Unit Processes (Dielectrics, metals, barriers, Wet, CMP, PVD, CVD, ALD, selective deposition/SAMs, patterning, advanced cleaning and surface treatment)
- Reliability and Failure analysis, characterization, techniques, and methods
- Advanced material/process characterization, system-technology & design-technology co-optimization, and modelling techniques
- Advanced packaging for 2.5D/3D, Monolithic 3D IC, hybrid bonding...

## ABSTRACT INFORMATION

Abstracts must be no more than 3 pages in length. Details of abstract submission, including a template may be found at <http://iitc2025.org/cfp/> which will open by the end of December. Submissions will be reviewed for acceptance as an oral presentation or poster. Accepted abstracts will be published digitally by IEEE as IITC Conference Proceedings without further changes.

More information <http://iitc2025.org>